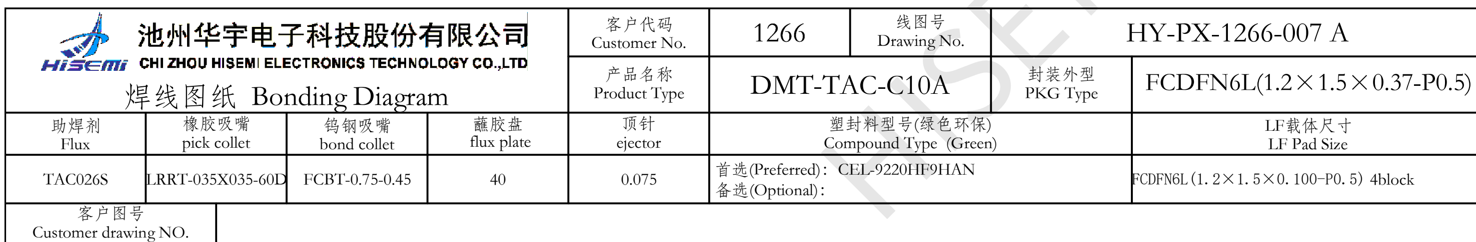
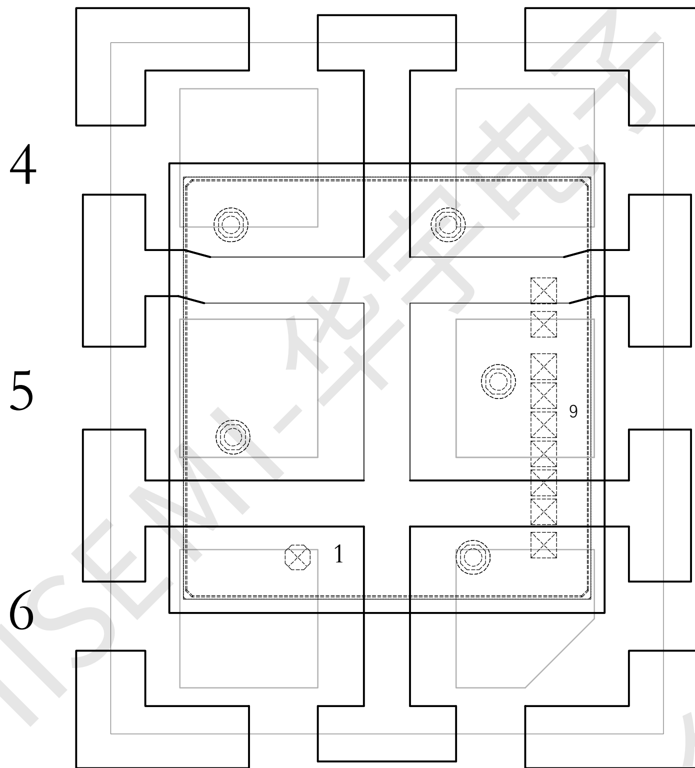
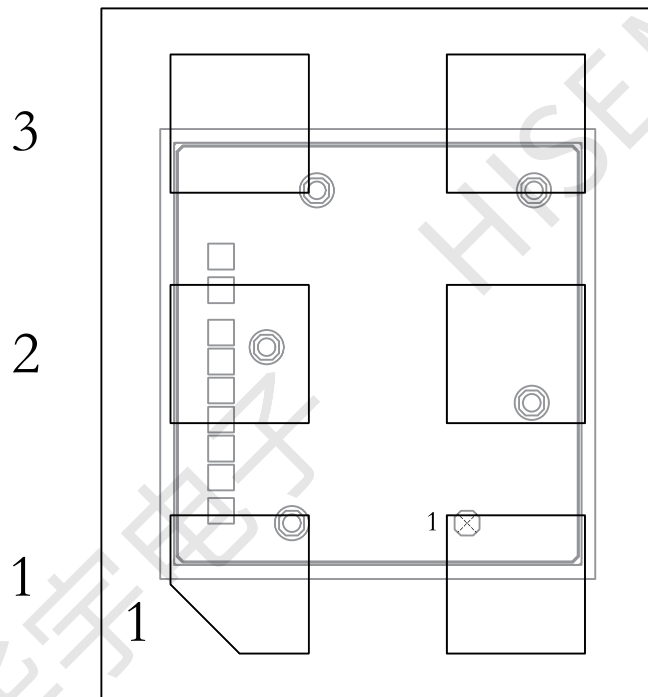


池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram				客户代码 Customer No.	1266	线图号 Drawing No.	HY-PX-1266-007 A
				产品名称 Product Type	DMT-TAC-C10A	封装外型 PKG Type	FCDFN6L(1.2×1.5×0.37-P0.5)
助焊剂 Flux	橡胶吸嘴 pick collet	钨钢吸嘴 bond collet	蘸胶盘 flux plate	顶针 ejector	塑封料型号(绿色环保) Compound Type (Green)		LF载体尺寸 LF Pad Size
TAC026S	LRRT-035X035-60D	FCBT-0.75-0.45	40	0.075	首选(Preferred): CEL-9220HF9HAN 备选(Optional):		FCDFN6L(1.2×1.5×0.100-P0.5) 4block
客户图号 Customer drawing NO.							

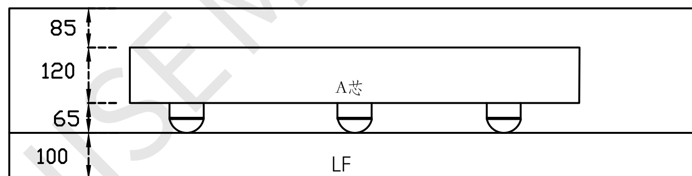


正面示意图



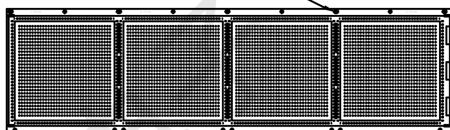
底部示意图

剖面图



框架传送方向（装片）：
L/F Direction（D/A）：

椭圆孔



实物图：
Chip photo:

特殊说明 Special Instructions：

DB注意：
1.FC芯片居中放置；
2.数字为非bump pad.

A芯： DIE A	芯片名称 Die name	0993C	芯片尺寸 Die Size	976.2*944.7(µm²) 38.43*37.19 (mil²)	凸点尺寸 Bump Size(um)	74	最小凸点节距 Min Bump Pitch(um)	296	凸点类型 Bump Type	pillar
	芯片类型 Chip type	Power	晶圆尺寸 Wafer Size	12	划片道宽度 Street line (µm)	60	凸点高度 BumpComposition/Height(um)	Cu32um/ Ni3um/ SnAg30um	凸点数量 No. of Bump	5
	是否激光切割 If laser	是/Yes 55nm (low-k)	减薄厚度 (µm) Wafer Thickness	120						

拟制 Prepared by		制图日期 Create Date	2026/3/20	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
研发审核 R&D Check		产品工程审核 PE Check		批准 Approved by		

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*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

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